BT139B series E

#### **GENERAL DESCRIPTION**

# Glass passivated, sensitive gate triacs in a plastic envelope suitable for surface mounting, intended for use in general purpose bidirectional switching and phase control applications, where high sensitivity is required in all four quadrants.

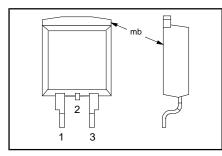
### **QUICK REFERENCE DATA**

| SYMBOL                                  | PARAMETER   | MAX.            | MAX.            | MAX.            | UNIT   |
|---|---|-----------------|-----------------|-----------------|--------|
| $V_{DRM}$                               | BT139B-<br>Repetitive peak off-state  | <b>500E</b> 500 | <b>600E</b> 600 | <b>800E</b> 800 | V      |
| I <sub>T(RMS)</sub><br>I <sub>TSM</sub> | voltages<br>RMS on-state current<br>Non-repetitive peak on-state<br>current | 16<br>140       | 16<br>140       | 16<br>140       | A<br>A |

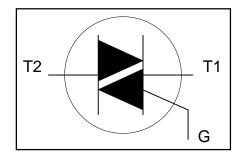
### **PINNING - SOT404**

| PIN | DESCRIPTION     |
|-----|-----------------|
| 1   | main terminal 1 |
| 2   | main terminal 2 |
| 3   | gate            |
| mb  | main terminal 2 |

# **PIN CONFIGURATION**



### **SYMBOL**



## **LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum System (IEC 134).

| SYMBOL  | PARAMETER   | CONDITIONS   | MIN.        |                              | MAX.                            |                    | UNIT                  |
|---|---|--|-------------|------------------------------|---------------------------------|--------------------|-----------------------|
| $V_{DRM}$   | Repetitive peak off-state voltages  |  | -           | <b>-500</b> 500 <sup>1</sup> | <b>-600</b><br>600 <sup>1</sup> | <b>-800</b><br>800 | V                     |
| I <sub>T(RMS)</sub>   | RMS on-state current<br>Non-repetitive peak<br>on-state current                       | full sine wave; $T_{mb} \le 99 ^{\circ}C$<br>full sine wave; $T_{j} = 25 ^{\circ}C$ prior to surge                   | -           |                              | 16                              |                    | А                     |
|   |   | t = 20 ms  | -           |                              | 140                             |                    | A                     |
| l²t<br>dl <sub>⊤</sub> /dt  | I <sup>2</sup> t for fusing<br>Repetitive rate of rise of<br>on-state current after   | t = 16.7  ms<br>t = 10  ms<br>$I_{TM} = 20 \text{ A}; I_G = 0.2 \text{ A};$<br>$dI_G/dt = 0.2 \text{ A}/\mu\text{s}$ | -           |                              | 150<br>98                       |                    | A<br>A <sup>2</sup> s |
|   | triggering  | T2+ G+<br>T2+ G-<br>T2- G-<br>T2- G+   | -<br>-<br>- |                              | 50<br>50<br>50<br>10            |                    | A/μs<br>A/μs<br>A/μs  |
| I <sub>GM</sub><br>V <sub>GM</sub>  | Peak gate current Peak gate voltage   | 12- 9+   | -<br>-      |                              | 2<br>5<br>5                     |                    | A/μs<br>A<br>V<br>W   |
| P <sub>GM</sub><br>P <sub>G(AV)</sub><br>T <sub>stg</sub><br>T <sub>j</sub> | Peak gate power Average gate power Storage temperature Operating junction temperature | over any 20 ms period  | -40<br>-40  |                              | 0.5<br>150<br>125               |                    | Ç<br>C<br>C           |

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<sup>1</sup> Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15  $A/\mu s$ .

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# THERMAL RESISTANCES

| SYMBOL              | PARAMETER   | CONDITIONS   | MIN.  | TYP.         | MAX.            | UNIT              |
|---------------------|---|--|-------|--------------|-----------------|-------------------|
| R <sub>th i-a</sub> | Thermal resistance junction to mounting base Thermal resistance junction to ambient | full cycle<br>half cycle<br>minimum footprint, FR4 board | 1 1 1 | -<br>-<br>55 | 1.2<br>1.7<br>- | K/W<br>K/W<br>K/W |

## STATIC CHARACTERISTICS

T<sub>i</sub> = 25 °C unless otherwise stated

| SYMBOL           | PARAMETER                 | CONDITIONS  |        | MIN. | TYP. | MAX. | UNIT |
|------------------|---------------------------|---|--------|------|------|------|------|
| I <sub>GT</sub>  | Gate trigger current      | $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$   |        |      |      |      |      |
|                  |                           |   | T2+ G+ | -    | 2.5  | 10   | mΑ   |
|                  |                           |   | T2+ G- | -    | 4.0  | 10   | mΑ   |
|                  |                           |   | T2- G- | -    | 5.0  | 10   | mΑ   |
|                  |                           |   | T2- G+ | -    | 11   | 25   | mΑ   |
| I <sub>L</sub>   | Latching current          | $V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$  |        |      |      |      |      |
|                  |                           |   | T2+ G+ | -    | 3.2  | 30   | mA   |
|                  |                           |   | T2+ G- | -    | 16   | 40   | mA   |
|                  |                           |   | T2- G- | -    | 4.0  | 30   | mA   |
|                  |                           |   | T2- G+ | -    | 5.5  | 40   | mA   |
| l I <sub>H</sub> | Holding current           | $V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$  |        | -    | 4.0  | 30   | mA   |
| V <sub>T</sub>   | On-state voltage          | $I_{T} = 20 \text{ A}$  |        | -    | 1.2  | 1.6  | V    |
| V <sub>GT</sub>  | Gate trigger voltage      | $\begin{vmatrix} \dot{V}_D = 12 \text{ V}; I_T = 0.1 \text{ A} \\ V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_i = 125  \end{vmatrix}$ | _      | -    | 0.7  | 1.5  | V    |
|                  |                           | $ V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_i = 125 $   | C C    | 0.25 | 0.4  | -    | V    |
| I <sub>D</sub>   | Off-state leakage current | $V_D = V_{DRM(max)}$ ; $T_j = 125$ °C   |        | -    | 0.1  | 0.5  | mA   |

## **DYNAMIC CHARACTERISTICS**

 $T_i = 25$  °C unless otherwise stated

| SYMBOL              | PARAMETER  | CONDITIONS   | MIN. | TYP. | MAX. | UNIT |
|---------------------|--|--|------|------|------|------|
| dV <sub>D</sub> /dt | Critical rate of rise of                             | $V_{DM} = 67\% V_{DRM(max)}; T_j = 125 °C;$  | -    | 50   | -    | V/μs |
| t <sub>gt</sub>     | off-state voltage<br>Gate controlled turn-on<br>time | exponential waveform; gate open circuit $I_{TM} = 20 \text{ A}$ ; $V_D = V_{DRM(max)}$ ; $I_G = 0.1 \text{ A}$ ; $dI_G/dt = 5 \text{ A}/\mu\text{s}$ | -    | 2    | -    | μs   |

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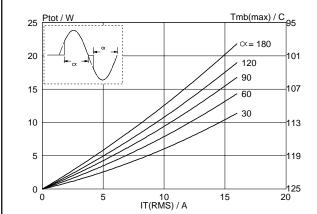


Fig.1. Maximum on-state dissipation,  $P_{tot}$ , versus rms on-state current,  $I_{T(RMS)}$ , where  $\alpha = conduction$  angle.

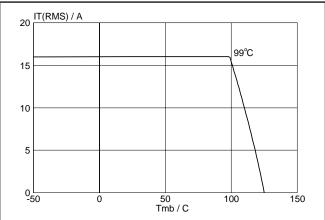


Fig.4. Maximum permissible rms current  $I_{T(RMS)}$ , versus mounting base temperature  $T_{mb}$ .

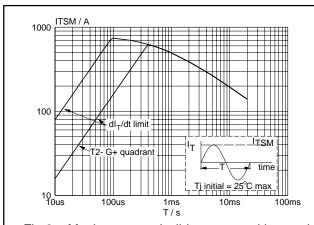


Fig.2. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus pulse width  $t_p$ , for sinusoidal currents,  $t_p \le 20$ ms.

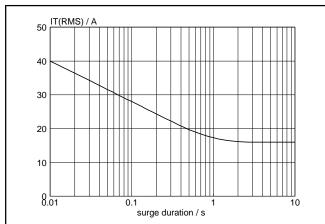


Fig.5. Maximum permissible repetitive rms on-state current  $I_{T(RMS)}$ , versus surge duration, for sinusoidal currents, f = 50 Hz;  $T_{mb} \le 99$ °C.

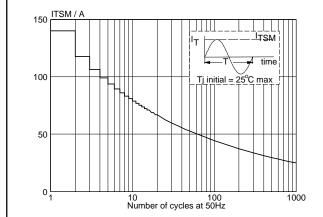


Fig.3. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus number of cycles, for sinusoidal currents, f = 50 Hz.

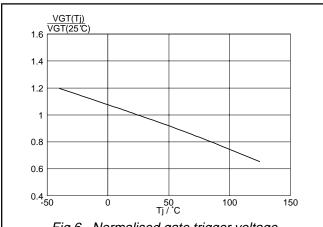
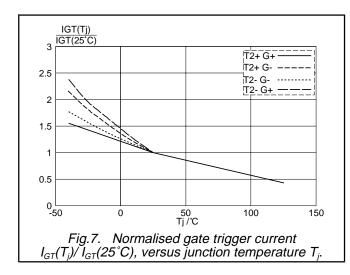
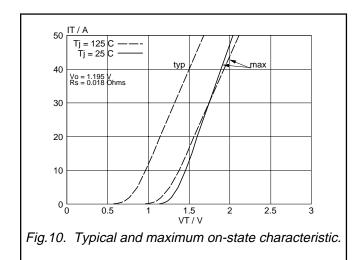
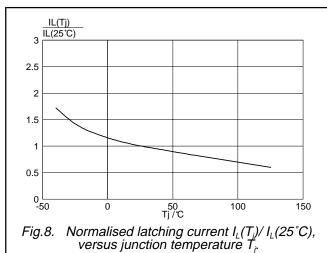


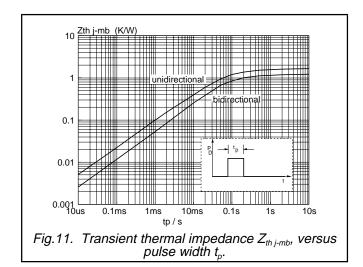
Fig.6. Normalised gate trigger voltage  $V_{GT}(T_j)/V_{GT}(25\,^{\circ}C)$ , versus junction temperature  $T_j$ .

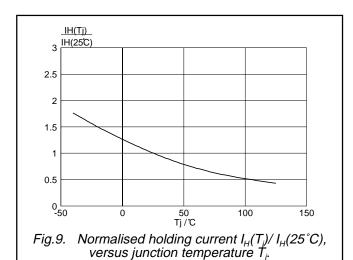
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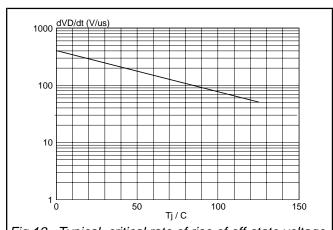
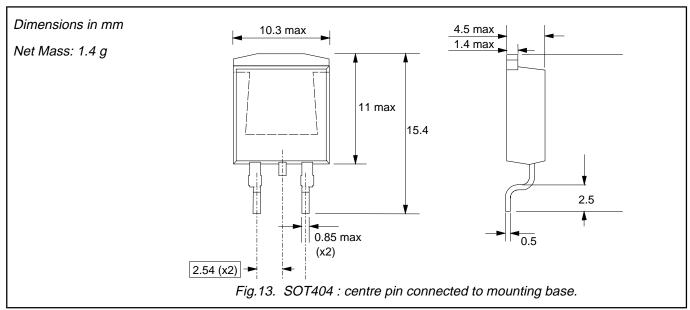


Fig.12. Typical, critical rate of rise of off-state voltage, dV<sub>D</sub>/dt versus junction temperature T<sub>i</sub>.

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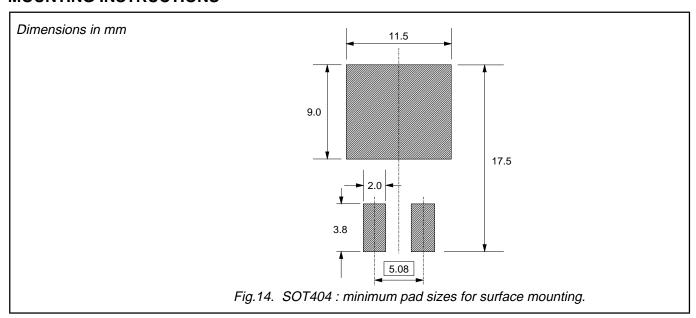
### **MECHANICAL DATA**



#### **Notes**

1. Epoxy meets UL94 V0 at 1/8".

## **MOUNTING INSTRUCTIONS**



#### **Notes**

1. Plastic meets UL94 V0 at 1/8".

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#### **DEFINITIONS**

| Data sheet status         |   |  |  |  |  |
|---------------------------|---|--|--|--|--|
| Objective specification   | This data sheet contains target or goal specifications for product development.       |  |  |  |  |
| Preliminary specification | This data sheet contains preliminary data; supplementary data may be published later. |  |  |  |  |
| Product specification     | This data sheet contains final product specifications.                                |  |  |  |  |

#### Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

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